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NOTICE TO SUBMIT RESPONSE 17 2003

TECHNOLOGY CENTER 2800

Patent Applicant

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Application No.: 10-2001-0007845

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Title of the Invention: Method and Apparatus for Automatically Controlling Output of
Laser Diode

According to Article 63 of the Korean Patent Law, the applicant is notified that the present application has been rejected for the reasons given below. Any Argument or Amendment which the applicant may wish to submit, must be submitted by December 29, 2002. An indefinite number of one-month extensions in the period for submitting a response may be obtained upon request, however no official confirmation of the acceptance of a request for an extension will be issued.

Reasons

The invention as claimed in claims 1 - 6 could have been easily invented by one of ordinary skill in the art prior to the filing of the application, and thus this application is rejected according to Article 29(2) of the Korean Patent Law.

The present invention relates to a method and an apparatus for automatically controlling an output of a laser diode in which a current power value is sampled and compared with a basic power value, and an output of the laser diode is controlled based on the comparison result. A cited reference (Japanese Laid-open Patent Publication No. hei 10-69664) provides an apparatus for controlling current of a laser diode by comparing a detector for detecting a power output from the laser diode with a sampler for sampling the power output from the laser diode. Thus, the present invention has very similar means to the cited reference. Therefore, the present invention could be considered to have easily

been invented from the cited reference.

For reference, and should be deleted from an operator unit outputting: and in claim 2.

Enclosure: Japanese Laid-open Patent Publication No. hei 10-069664 (published on March 10, 1998)

26 October 2002

Jin-suk Song/Examiner
Examination Division 4
Korean Industrial Property Office